



PIC16C715

PIC16C715 Data Sheet Errata

The PIC16C715 parts you have received conform functionally to the Device Data Sheet (DS30272A), except for the anomalies described below.

None.

PIC16C715

Clarifications/Corrections to the Data Sheet:

In the Device Data Sheet (DS30272A), the following clarifications and corrections should be noted.

1. Module: Core (DC Characteristics)

Section 13.3 has changed as shown below.

13.3 DC Characteristics: PIC16C715-04 (Commercial, Industrial, Extended) PIC16C715-10 (Commercial, Industrial, Extended) PIC16C715-20 (Commercial, Industrial, Extended) PIC16LC715-04 (Commercial, Industrial)

Standard Operating Conditions (unless otherwise stated)							
DC CHARACTERISTICS							
Operating temperature 0°C ≤ TA ≤ +70°C (commercial) -40°C ≤ TA ≤ +85°C (industrial) -40°C ≤ TA ≤ +125°C (extended)							
Operating voltage VDD range as described in DC spec Section 13.1 and Section 13.2.							
Param No.	Characteristic	Sym	Min	Typ†	Max	Units	Conditions
D030 D031	Input Low Voltage I/O ports: with TTL buffer	VIL	Vss Vss	— —	0.15VDD 0.8V	V V	For entire VDD range 4.5 ≤ VDD ≤ 5.5V

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

- Note 1:** In RC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C7X be driven with external clock in RC mode.
- 2:** The leakage current on the MCLR pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.
- 3:** Negative current is defined as coming out of the pin.

2. Module: Analog-to-Digital Converter

Figure 7-2, page 38, should change from bit 6-3 to bit 4-3, which will include the information listed below:

FIGURE 7-2: ADCON0 REGISTER (ADDRESS 1Fh)

bit 4-3: CHS1:CHS0: Analog Channel Select bits 00 = channel 0, (RA0/AN0) 01 = channel 1, (RA1/AN1) 10 = channel 2, (RA2/AN2) 11 = channel 3, (RA3/AN3)

3. Module: Core (Pinouts)

Table 3-1, page 9, should show the following information:

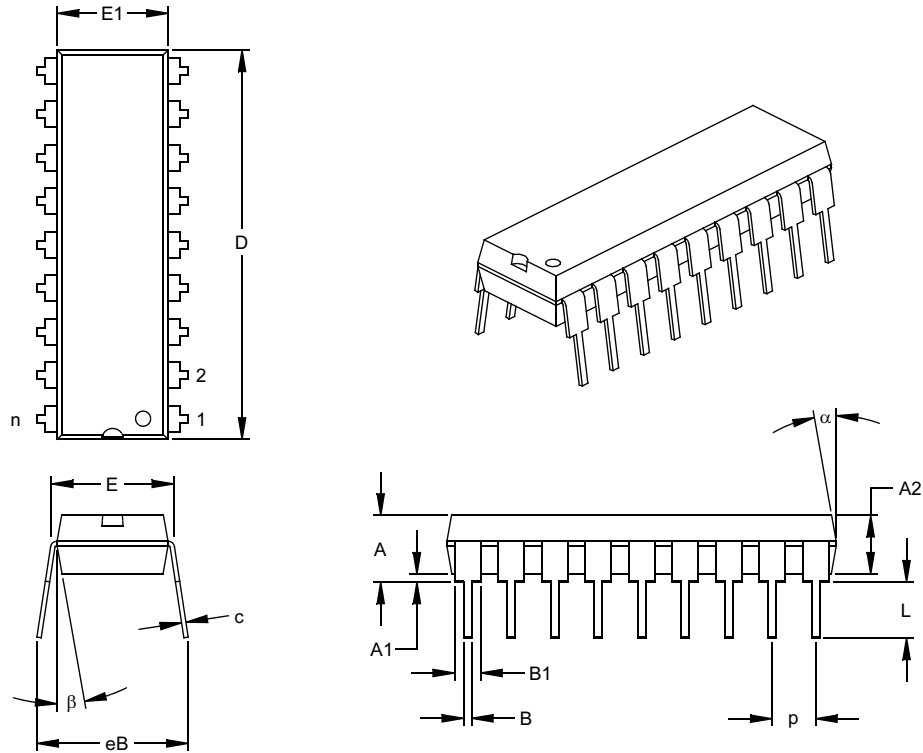
Table 3-1: PIC16C710/711/715 PINOUT DESCRIPTION

Vss	5	5, 6	5	P	—	Ground reference for logic and I/O pins.
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4. Module: Packaging

The package information contained in the data sheet is incorrect. Please refer to the following tables for correct package data.

18-Lead Plastic Dual In-line (P) – 300 mil (PDIP)



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		18			18	
Pitch	p		.100			2.54	
Top to Seating Plane	A	.140	.155	.170	3.56	3.94	4.32
Molded Package Thickness	A2	.115	.130	.145	2.92	3.30	3.68
Base to Seating Plane	A1	.015			0.38		
Shoulder to Shoulder Width	E	.300	.313	.325	7.62	7.94	8.26
Molded Package Width	E1	.240	.250	.260	6.10	6.35	6.60
Overall Length	D	.890	.898	.905	22.61	22.80	22.99
Tip to Seating Plane	L	.125	.130	.135	3.18	3.30	3.43
Lead Thickness	c	.008	.012	.015	0.20	0.29	0.38
Upper Lead Width	B1	.045	.058	.070	1.14	1.46	1.78
Lower Lead Width	B	.014	.018	.022	0.36	0.46	0.56
Overall Row Spacing	§ eB	.310	.370	.430	7.87	9.40	10.92
Mold Draft Angle Top	α	5	10	15	5	10	15
Mold Draft Angle Bottom	β	5	10	15	5	10	15

* Controlling Parameter
 § Significant Characteristic

Notes:

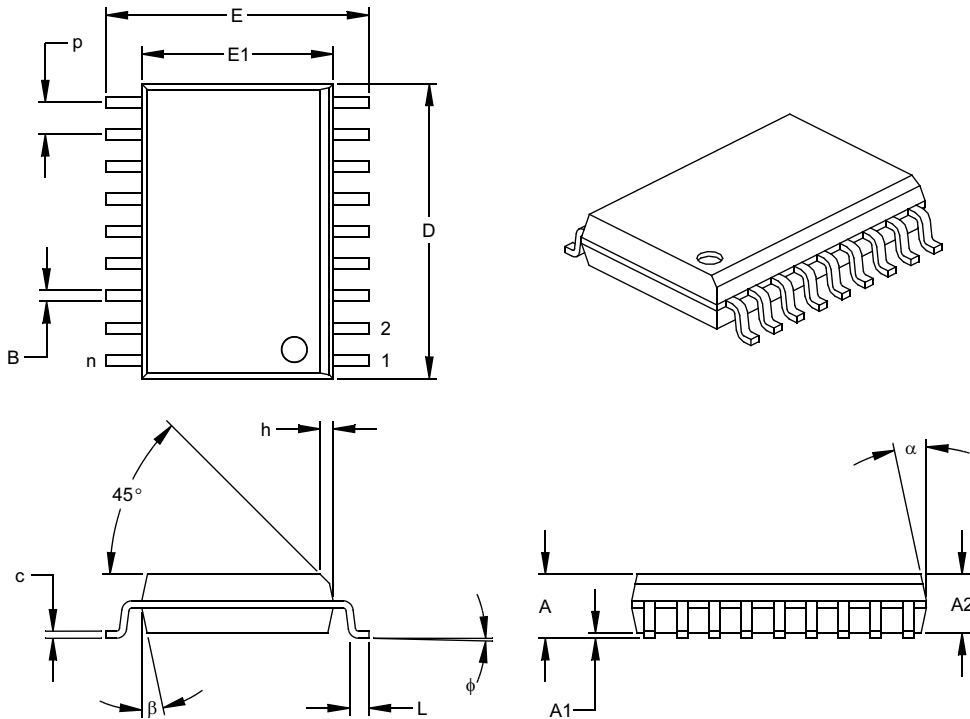
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.

JEDEC Equivalent: MS-001

Drawing No. C04-007

PIC16C715

18-Lead Plastic Small Outline (SO) – Wide, 300 mil (SOIC)



Dimension Limits	Units	INCHES*			MILLIMETERS		
		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		18			18	
Pitch	p		.050			1.27	
Overall Height	A	.093	.099	.104	2.36	2.50	2.64
Molded Package Thickness	A2	.088	.091	.094	2.24	2.31	2.39
Standoff §	A1	.004	.008	.012	0.10	0.20	0.30
Overall Width	E	.394	.407	.420	10.01	10.34	10.67
Molded Package Width	E1	.291	.295	.299	7.39	7.49	7.59
Overall Length	D	.446	.454	.462	11.33	11.53	11.73
Chamfer Distance	h	.010	.020	.029	0.25	0.50	0.74
Foot Length	L	.016	.033	.050	0.41	0.84	1.27
Foot Angle	φ	0	4	8	0	4	8
Lead Thickness	c	.009	.011	.012	0.23	0.27	0.30
Lead Width	B	.014	.017	.020	0.36	0.42	0.51
Mold Draft Angle Top	α	0	12	15	0	12	15
Mold Draft Angle Bottom	β	0	12	15	0	12	15

* Controlling Parameter
 § Significant Characteristic

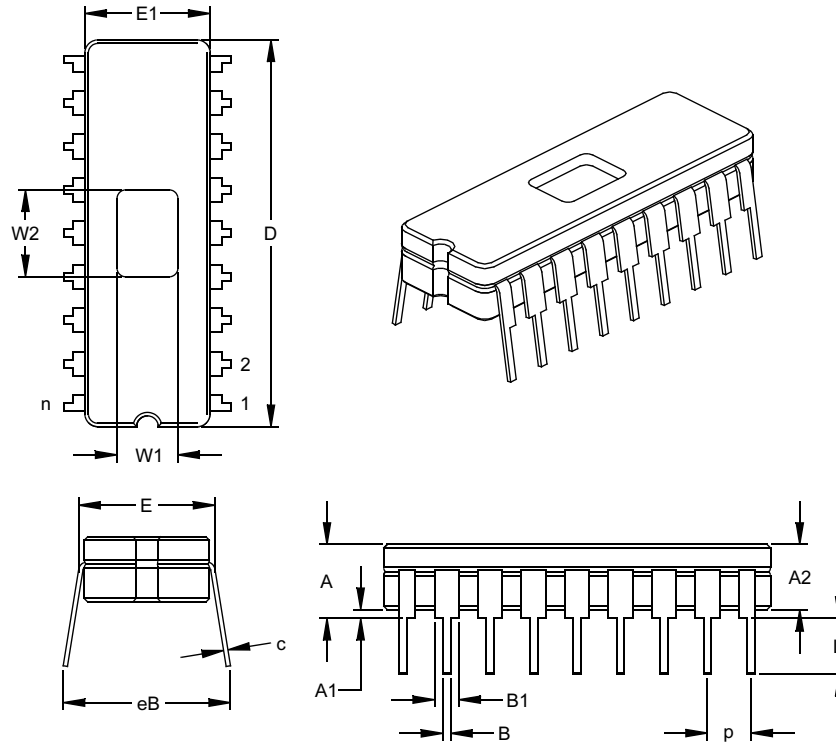
Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.

JEDEC Equivalent: MS-013

Drawing No. C04-051

18-Lead Ceramic Dual In-line with Window (JW) – 300 mil (CERDIP)

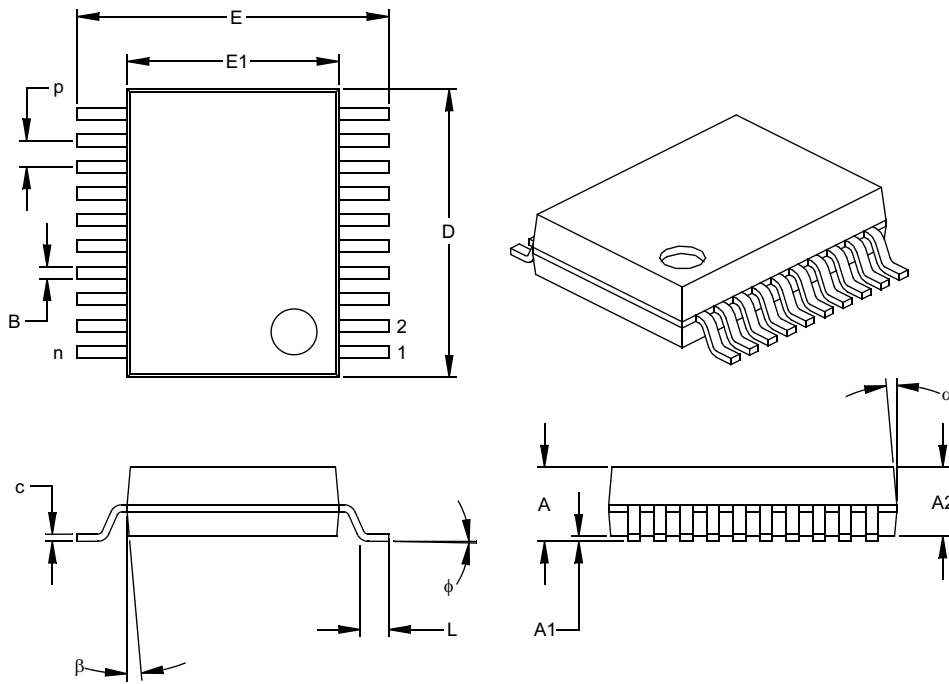


Dimension Limits	Units	INCHES*			MILLIMETERS		
		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		18			18	
Pitch	p		.100			2.54	
Top to Seating Plane	A	.170	.183	.195	4.32	4.64	4.95
Ceramic Package Height	A2	.155	.160	.165	3.94	4.06	4.19
Standoff	A1	.015	.023	.030	0.38	0.57	0.76
Shoulder to Shoulder Width	E	.300	.313	.325	7.62	7.94	8.26
Ceramic Pkg. Width	E1	.285	.290	.295	7.24	7.37	7.49
Overall Length	D	.880	.900	.920	22.35	22.86	23.37
Tip to Seating Plane	L	.125	.138	.150	3.18	3.49	3.81
Lead Thickness	c	.008	.010	.012	0.20	0.25	0.30
Upper Lead Width	B1	.050	.055	.060	1.27	1.40	1.52
Lower Lead Width	B	.016	.019	.021	0.41	0.47	0.53
Overall Row Spacing	§ eB	.345	.385	.425	8.76	9.78	10.80
Window Width	W1	.130	.140	.150	3.30	3.56	3.81
Window Length	W2	.190	.200	.210	4.83	5.08	5.33

* Controlling Parameter
 § Significant Characteristic
 JEDEC Equivalent: MO-036
 Drawing No. C04-010

PIC16C715

20-Lead Plastic Shrink Small Outline (SS) – 209 mil, 5.30 mm (SSOP)



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		20			20	
Pitch	p		.026			0.65	
Overall Height	A	.068	.073	.078	1.73	1.85	1.98
Molded Package Thickness	A2	.064	.068	.072	1.63	1.73	1.83
Standoff §	A1	.002	.006	.010	0.05	0.15	0.25
Overall Width	E	.299	.309	.322	7.59	7.85	8.18
Molded Package Width	E1	.201	.207	.212	5.11	5.25	5.38
Overall Length	D	.278	.284	.289	7.06	7.20	7.34
Foot Length	L	.022	.030	.037	0.56	0.75	0.94
Lead Thickness	c	.004	.007	.010	0.10	0.18	0.25
Foot Angle	φ	0	4	8	0.00	101.60	203.20
Lead Width	B	.010	.013	.015	0.25	0.32	0.38
Mold Draft Angle Top	α	0	5	10	0	5	10
Mold Draft Angle Bottom	β	0	5	10	0	5	10

* Controlling Parameter

§ Significant Characteristic

Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.

JEDEC Equivalent: MO-150

Drawing No. C04-072

APPENDIX A: REVISION HISTORY

Rev. A Document 9/2000

First revision of this document.

Rev. B Document 6/2001

Under Clarifications/Corrections to the Data Sheet, added issue 2 (Analog-to-Digital Converter) and issue 3 (Core).

Rev. C Document 3/2003

Under Clarifications/Corrections to the Data Sheet, Item 4, Packaging: correct package data was added.

PIC16C715

NOTES:

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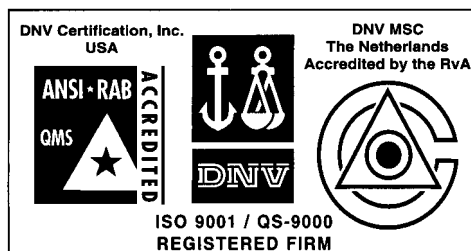
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